Silicon P Channel MOS FET High Speed Switching

HITACHI

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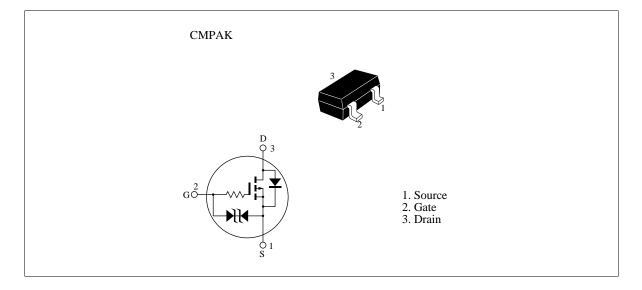
Features

Low on-resistance

$$\begin{split} R_{\rm DS} &= 4.1 \quad typ. \; (V_{\rm GS} \;\; = -4 \; V \; , \; I_{\rm D} = -50 \; mA) \\ R_{\rm DS} &= 6.0 \;\; typ. \; (V_{\rm GS} \;\; = -2.5 \; V \; , \; I_{\rm D} = -50 \; mA) \end{split}$$

- 2.5 V gate drive device.
- 2.5 V gate unive device.
- Small package (CMPAK)

Outline





Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Ratings	Unit
Drain to source voltage	V _{DSS}	-20	V
Gate to source voltage	V _{GSS}	±10	V
Drain current	I _D	-100	mA
Drain peak current	Note1 D(pulse)	-400	mA
Body-drain diode reverse drain current	I _{DR}	-100	mA
Channel dissipation	Pch Note 2	300	mW
Channel temperature	Tch	150	°C
Storage temperature	Tstg	–55 to +150	°C

Note: 1. PW 10 µs, duty cycle 1%

2. Value on the alumina ceramic board (12.5x 20 x0.7 mm)

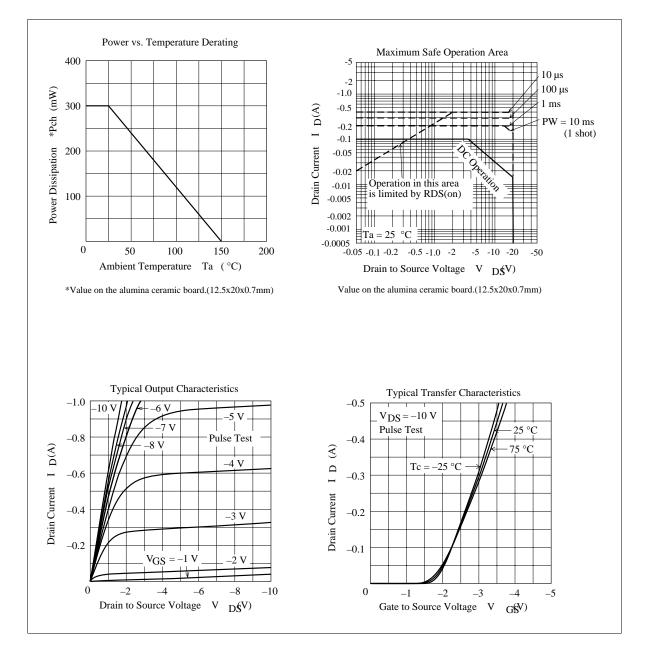
Electrical Characteristics (Ta = 25°C)

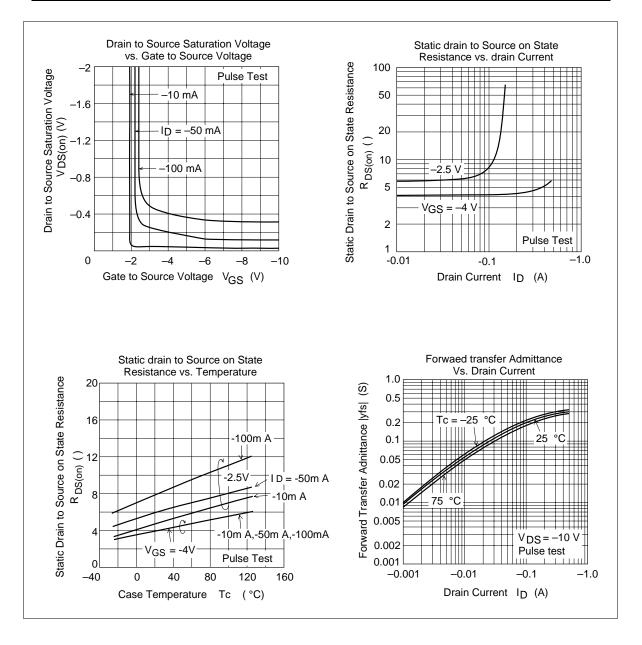
Item	Symbol	Min	Тур	Мах	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	-20	—	—	V	$I_{\rm D}$ = -100 µA, $V_{\rm GS}$ = 0
Gate to source breakdown voltage	$V_{(BR)GSS}$	±10	—	—	V	$I_{\rm G} = \pm 100 \ \mu A, \ V_{\rm DS} = 0$
Gate to source leak current	I _{GSS}	_		±5	μA	$V_{GS} = \pm 8 V, V_{DS} = 0$
Zero gate voltege drain current	I _{DSS}	_	—	-1	μA	$V_{\rm DS} = -20$ V, $V_{\rm GS} = 0$
Gate to source cutoff voltage	$V_{\text{GS(off)}}$	-0.8		-1.8	V	$I_{D} = -10 \mu A, V_{DS} = -5 V$
Static drain to source on state	$R_{DS(on)}$	_	4.1	5.0		I_{D} = -50 mA, V_{GS} = -4 V ^{Note 3}
resistance	R _{DS(on)}	_	6.0	8.5		I_D = -50 mA, V_{GS} = -2.5 V ^{Note 3}
Forward transfer admittance	y _{fs}	94	144	—	mS	I_D = -50 mA, V_{DS} = -10 V ^{Note 3}
Input capacitance	Ciss	_	28	—	pF	V _{DS} = -10 V
Output capacitance	Coss	_	21	—	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	—	7	—	pF	f = 1 MHz
Turn-on delay time	t _{d(on)}	—	30	—	ns	$I_{\rm D}$ = -50 mA, $V_{\rm GS}$ = -4 V
Rise time	t,	_	90	—	ns	R _L = 200
Turn-off delay time	t _{d(off)}	_	87	_	ns	
Fall time	t _f	—	97	—	ns	

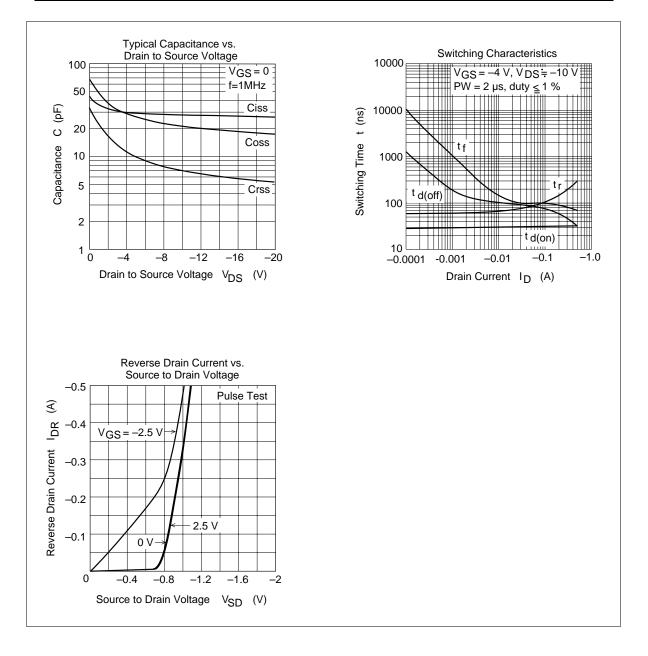
Note: 3. Pulse test

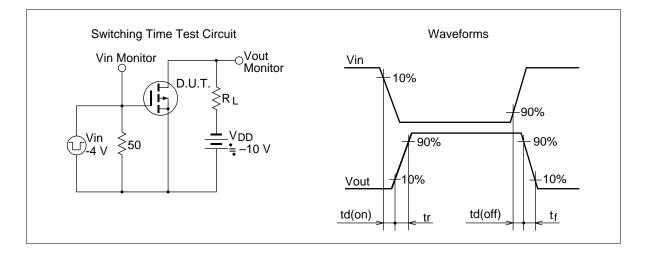
4. Marking is CP

Main Characteristics

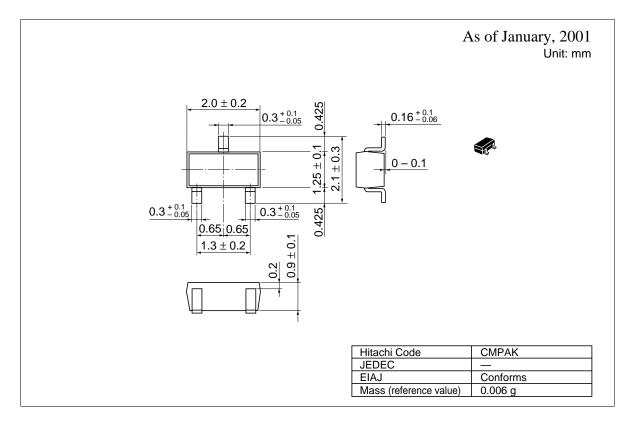








Package Dimensions



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